12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260826002.1	PCN Issued	August 27, 2026
Qualification of RFAB as an additional Fab site option using qualified Process Technology, Die Revision, Datasheet update, TI Malaysia and BOM options for select devices		Sample request deadline:	October 26, 2026
		Estimated 1st ship date:	November 25, 2026
***Sample requests received after** October 26, 2026* **will not be supported.**			

Change type(s)
Assembly Site
Assembly Material
Packing/Shipping/Labeling
Design
Data Sheet/Electrical Specification
Wafer Fab Site
Wafer Fab Material
Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9), Assembly site TI Malaysia and BOM options for select devices as listed below in the product affected section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
FFAB	ASLNONC10	200mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

Group 1:

	Current	Additional
Wire bond diam/type	Cu, 0.96	Cu, 0.8

Group 2:

	Current	Additional
Assembly Site	FMX	MLA
Wire bond diam/type	Cu, 0.96	Cu, 0.8

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.

Changes from Revision A (March 2005) to Revision B (August 2026) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Removed Oredering Information table 4
- Added the *ESD Ratings* table.....5
- Added the *Thermal Information* table..... 6
- Updated I_{CCD} values in the *Electrical Characteristics* table. 7
- Updated the t_{pd}, t_{en}, and t_{dis} values in the *Switching Characteristics* table 7
- Added the latest typical curve data to the *Typical Characteristics* section..... 9

Changes from Revision C (June 2018) to Revision D (August 2026) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Added the DYY package to the document..... 1
- Added operating free-air temperature minimum and maximum values in the *Recommended Operating Conditions* table.....4
- Updated all values in the *Thermal Information* table 5
- Added the DYY package to the *Thermal Information* table 5
- Changed the typical I_{CCD} per input control value in the *Electrical Characteristics* table from 0.04 to 0.23..... 5
- Changed the maximum I_{CCD} per input control value in the *Electrical Characteristics* table from 0.05 to 0.25...5
- Added the *Electrical Characteristics: DYY Package* table.....6
- Added the *Switching Characteristics: DYY Package* table.....7
- Added the latest typical curve data to the *Typical Characteristics* section..... 8

Changes from Revision B (March 2005) to Revision C (August 2026) **Page**

- Deleted the GQN package from the document..... 1
- Updated the number formatting for tables, figures, and cross-references throughout the document 1
- Removed Ordering Information table. 1
- Added the ESD Ratings table.....3
- Added the *Thermal Information* table and moved $R_{\theta JA}$ values to the table.....4
- Updated the maximum *Per input control* parameter in the *Electrical Characteristics* table from 0.35 to 0.45....4
- Updated the maximum V_{CC} rating for t_{en} and t_{dis} in the *Switching Characteristics* table.....5

Changes from Revision B (March 2005) to Revision C (August 2026) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Added *Device Information* table, *ESD Ratings* table, *Device Functional Modes*, *Typical Characteristics*, *Device and Documentation Support* sections, and *Mechanical, Packaging, and Orderable Information* section. 1
- Changed pin 16 from: *B9* to: *B3* in the RGY package.....4
- Removed the Ordering Information table..... 4
- Added the Thermal Information table..... 6
- Updated the C_{in} values in the Electrical Characteristics table.....6
- Updated the t_{en} and t_{dis} values in the Switching Characteristics table..... 7

TEXAS INSTRUMENTS

SN74CB3Q3257

SCDS135F – SEPTEMBER 2003 – REVISED AUGUST 2026

Changes from Revision E (December 2024) to Revision F (August 2026) **Page**

- Updated the number formatting for tables, figures, and cross-references throughout the document 1
- Updated the *Thermal Information* table values 5
- Updated the maximum value of the *Per input control* parameter in the *Electrical Characteristics - PKG = RGY, PW, DBQ, DGV* table from 0.35 to 0.45..... 5
- Updated new package information to the *Switching Characteristics* tables 7
- Updated the *Typical Characteristics* section.....8

TEXAS INSTRUMENTS

SN74CB3Q3244

SCDS154C – OCTOBER 2003 – REVISED AUGUST 2026

Changes from Revision B (December 2004) to Revision C (August 2026) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document 1
- Deleted the *Ordering Information* table from the document..... 1
- Deleted the GQN package from the document..... 4
- Added the *ESD Ratings* table.....5
- Added the *Thermal Information* table and moved $R_{\theta JA}$ to the table..... 6
- Changed the typical I_{CCD} per input control value in the *Electrical Characteristics* table from 0.14 to 0.3..... 7
- Changed the maximum I_{CCD} per input control value in the *Electrical Characteristics* table from 0.15 to 0.45... 7
- Updated the maximum V_{CC} values for t_{dis} in the *Switching Characteristics* table..... 7
- Added the latest typical curve data to the *Typical Characteristics* section..... 8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74CB3Q3251	SCDS173A	SCDS173B	https://www.ti.com/product/SN74CB3Q3251
SN74CB3Q3253	SCDS145C	SCDS145D	https://www.ti.com/product/SN74CB3Q3253
SN74CB3Q3245	SCDS124B	SCDS124C	https://www.ti.com/product/SN74CB3Q3245
SN74CB3Q3345	SCDS144B	SCDS144C	https://www.ti.com/product/SN74CB3Q3345
SN74CB3Q3257	SCDS135E	SCDS135F	https://www.ti.com/product/SN74CB3Q3257
SN74CB3Q3244	SCDS154B	SCDS154C	https://www.ti.com/product/SN74CB3Q3244

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• Physical aspects of the device have changed • Device quality has improved • Request the Supporting Data Packet and review updated Datasheets for more details on the changes. Evaluating samples is encouraged.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A	**-**

Assembly Site Information (Group 2)

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Mexico (FMX)	MEX	MEX	Aguascalientes
TI Malaysia (MLA)	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label):

Products Affected: Group 1			
SN74CB3Q3251PWR	SN74CB3Q3251PWRG4	SN74CB3Q3253PWR	
SN74CB3Q3257PWR	SN74CB3Q3257PWRG4		

Products Affected: Group 2			
SN74CB3Q3244PWR	SN74CB3Q3244PWRG4	SN74CB3Q3245PWR	SN74CB3Q3345PWR
SN74CB3Q3345PWRG4	SN74CB3Q3251DBQR	SN74CB3Q3253DBQR	SN74CB3Q3253DBQRG4
SN74CB3Q3257DBQR	SN74CB3Q3244DBQR	SN74CB3Q3244DBQRG4	SN74CB3Q3245DBQR

Qualification Report

SN74CB3Q3XXX devices MLA
Approve Date 16-June-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3245PWR	Qual Device: SN74CB3Q3244PWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: LM324BIPWR	QBS Product Reference: SN74CB3Q3245RGYR	QBS Product Reference: SN74CB3Q3244RGYR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	3/231/0	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/3000/0	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3245PWR is qualified at MSL1 260C
- Qual Device SN74CB3Q3244PWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2409-028

Qualification Report

SN74CB3Q32XX MLA
Approve Date 26-June-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3244DBQR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74LV8T245DGSR	QBS Package Reference: GD75232DBR	QBS Package Reference: SN74AC165PWRQ1	QBS Product Reference: SN74CB3Q3244RGYR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	1/77/0	1/77/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	1/77/0	1/45/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	1/45/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3244DBQR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74LV8T245DGSR	QBS Package Reference: GD75232DBR	QBS Package Reference: SN74AC165PWRQ1	QBS Product Reference: SN74CB3Q3244RGYR
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3244DBQR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2409-032

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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